Texas Instruments Inc. Search results for "TAS5122DCARG4"

Current Production Information								
TI Part Number		TAS5122DCARG4	TAS5122DCARG4		Assembly Site		TI TAIWAN A/T	
Lead/Ball Finish		CU NIPDAU	CU NIPDAU		Package Type / Pins		DCA 56	
Planned Lead/Ball Finish					Package Body Size (WxLxH) mm		6.1x14x1.15	
MSL / Reflow Ratings		Level-3-260C-168 H	Level-3-260C-168 HR		Total Device Mass (mg)		236.9346660000002	
Environmental Ratings Informat	tion							
Part Number Type		Pb-Free	Pb-Free		JIG Material Content Compliance		Level A & B	
RoHS & High-Temp Compliant		Υ	Υ		Green Compliant		Y	
Pb-Free (RoHS) Conversion Date		01-Feb-2005 (DC 0506)		Green Conversion Date		01-Feb-2005 (DC 0506)		
Pb-Free (RoHS) Available Supply Date		01-Aug-2005	01-Aug-2005		Green Available Supply Date		01-Aug-2005	
Component Information								
				Homogeneous Material	Level	Component Level		
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	opm	
Bond Wire		•	• • •					
Metallurgy	Gold	7440-57-5	1.19988	99.9922	999922	0.5064	5064	
Trace Metal	Bervllium	7440-41-7	0.000012	0.001	10	0	0	
Trace Metal	Calcium	7440-70-2	0.000014	0.0012	11	0	0	
Trace Metal	Indium	7440-74-6	0.000037	0.0031	30	0	0	
Trace Metal	Silver	7440-22-4	0.00003	0.0025	25	0	0	
Sub-Total			1.199973	100	1000000	0.5065	5064	
Die Attach Adhesive								
Conductive Material	Silver	7440-22-4	0.14	70	700000	0.0591	590	
Polymer	Εροχγ		0.018	9	89999	0.0076	75	
Reactive Diluent	Proprietary Material		0.042	21	210000	0.0177	177	
Sub-Total			0.2	100	1000000	0.0844	842	
Lead Frame								
Base Metal	Copper	7440-50-8	89.86755	97.425	974250	37,9293	379292	
Base Metal	Iron	7439-89-6	2.213827	2.4	23999	0.9344	9343	
Base Metal	Lead	7439-92-1	0.027673	0.03	300	0.0117	116	
Base Metal	Phosphorus	7723-14-0	0.013836	0.015	149	0.0058	58	
Base Metal	Tin	7440-31-5	0.027673	0.03	300	0.0117	116	
Base Metal	Zinc	7440-66-6	0.092243	0.1	1000	0.0389	389	
Sub-Total			92.242802	100	1000000	38.9317	389314	
Lead Frame Plating								
Plating	Gold	7440-57-5	0.039858	1.5	15000	0.0168	168	
Plating	Nickel	7440-02-0	2.398123	90.25	902500	1.0121	10121	
Plating	Palladium	7440-05-3	0.219219	8.25	82500	0.0925	925	
Sub-Total			2.6572	100	1000000	1.1215	11214	
Mold Compound								
Coloring	Carbon Black	1333-86-4	0.528539	0.4	4000	0.2231	2230	
Filler	Fused Silica	60676-86-0	112.314487	85	849999	47.4031	474031	
Flame Retardant Additive	Metal Oxide		1.189212	0.9	8999	0.5019	5019	
Hardener	Biphenyl hardener		3.964041	3	30000	1.6731	16730	
Hardener	Phenolic Novolac		1.189212	0.9	8999	0.5019	5019	
Hardener	Proprietary Hardener		1.189212	0.9	8999	0.5019	5019	
Other additives	Catalyst Mold Release Adhesion Agent		1.717751	1.3	13000	0.725	7249	
Polymer	Biphenyl Epoxy		5.285388	4	40000	2.2307	22307	
Stress Relief Agent	Proprietary		0.792808	0.6	5999	0.3346	3346	
Stress Relief Agent	Silicone		3.964041	3	30000	1.6731	16730	
Sub-Total			132.134691	100	1000000	55.7684	557680	
Semiconductor Device								
Silicon Chip	Doped Silicon	7440-21-3	8.5	100	1000000	3.5875	35874	
Sub-Total			8.5	100	1000000	3.5875	35874	
Total			236,934666			100	100000	
			200.704000			100		

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Material Declaration Certificate for Semiconductor Products

TI certifies that the material content information provided by TI as of the date of disclosure is representative and accurate. TI semiconductor products designated by TI as "Pb-Free" or "Green" (defined below) do not exceed any of the Joint Industry Guide (JIG) Level-A Substance thresholds and are compliant with the requirements of the European Union's Restriction on Use of Hazardous Substances ("RoHS") Directive, 2002/95/EC.

For TI semiconductor products NOT designated as "Pb-Free" or "Green", these products are RoHS compliant with the exception of Lead (Pb) which may be found in the leadframe plating or solder balls, or in RoHS exempt applications such as high-temperature solder die attach (exemption 7a) and flip-chip solder bumps (exemption 15). This situation is known as RoHS-5 or "5 of 6" compliant.

JIG Level-A Banned Substances	Threshold, Homogeneous Level (1)
Asbestos	Not intentionally added
Azo colorants	Not intentionally added
	75 ppm, Not intentionally added
RoHS - Cadmium/Cadmium Compounds	(RoHS threshold = 100ppm)
RoHS - Hexavalent Chromium/Hex.Chromium.Compounds	1000 ppm, Not intentionally added
RoHS - Lead/Lead Compounds	1000 ppm, Not intentionally added
RoHS - Mercury/Mercury Compounds	1000 ppm, Not intentionally added
	Class I : Not intentionally added
Ozone Depleting Substances	Class II: 1000ppm
RoHS - Polybrominated Biphenyls (PBBs)	1000 ppm, Not intentionally added
RoHS - Polybrominated Diphenyl Ethers (PBDEs)	1000 ppm, Not intentionally added
Polychlorinated Biphenyls (PCBs)	1000 ppm, Not intentionally added
Polychlorinated Naphthalenes (>3 Chlorine atoms)	1000 ppm, Not intentionally added
Radioactive Substances	1000 ppm, Not intentionally added
Shortchain Chlorinated Paraffins	1000 ppm, Not intentionally added
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	1000 ppm, Not intentionally added
Tributyl Tin Oxide (TBTO)	1000 ppm, Not intentionally added
(1) Threshold does not apply to applications covered by a RoHS substance exemption	٦.

Regarding the EU Directive 2004/12/EC concerning Packaging and Packaging Waste, TI's packing materials (boxes, trays, etc) comply with the directive's requirement that the total concentration of the 4 heavy metals (cadmium, hexavalent chromium, lead, and mercury) must not exceed 100 ppm. Material content details for TI's packing materials are available at www.ti.com/ecoinfo.

TI bases its material content knowledge on information provided by third parties and has taken and continues to take commercially reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain limited information to be proprietary, and thus CAS numbers and other limited information may not be available for release. TI's standard warranty and limitation of liability provisions of TI's Standard Terms and Conditions (available at http://www.ti.com/sc/docs/stdterms.htm) apply to the representations herein unless otherwise provided by a written contract or other agreement signed by the parties.

Signature: (click here for signed certificate)

Name/Title: Cindy Allen, Vice President, Worldwide Quality

Date: September 27, 2006

Pb-Free: TI defines "Pb-Free" or "RoHS Compliant" to mean semiconductor products that are compliant with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials unless exempt. Where designed to be soldered at high temperatures, TI "Pb-Free" and "RoHS Compliant" products are suitable for use in specified lead-free processes.

Green: TI defines "Green" to mean Pb-Free/RoHS Compliant and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material).